

Appl. No. 10/667,904  
Amdt. dated April 5, 2005  
Reply to Office Action of December 8, 2004

PATENT

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

1. (Currently Amended) An embossing system, comprising:  
a sleeve having a first part and a second part;  
a stencil being adapted to be positioned between the sleeve first part and sleeve second part; and  
a form being adapted to be positioned between the stencil and either the sleeve first part or sleeve second part, and having at least one projection that maintains a clearance between a surface of the stencil and a surface of the form distinct from the at least one projection when the form is compressed towards the stencil while positioned in the sleeve.
2. (Original) The embossing system of claim 1, wherein the embossing system is adapted to accept embossing material between the form and the stencil.
3. (Original) The embossing system of claim 1, wherein an adhesive is disposed between the form and the sleeve first part or the sleeve second part to hold the form stationary relative to the sleeve.
4. (Original) The embossing system of claim 3, wherein static vinyl is disposed between the form and the sleeve first part or the sleeve second part to hold the form stationary relative to the sleeve.
5. (Original) The embossing system of claim 1, wherein an adhesive holds the stencil in place against the sleeve first part or the sleeve second part.
6. (Original) The embossing system of claim 1, wherein the stencil is made of a metallic material.

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7. (Original) The embossing system of claim 1, wherein the form is made of a plastic material.

8. (Original) The embossing system of claim 1, wherein the sleeve first part and the sleeve second part are connected by a hinge.

9. (Currently Amended) An embossing system, comprising:  
a force transfer assembly comprising:  
a first cover, an opposite second cover; and  
a hinge connecting said first cover and said second cover; and  
said force transfer assembly further comprising a stencil and an opposing vacuum formed plastic form positioned internal of the force transfer assembly, said stencil and said form being adapted to sandwich an embossing material between said stencil and said form;  
wherein at least one projection on the form operates to maintain a clearance between a surface of the form distinct from the at least one projection and the stencil when the embossing system is compressed.

10. (Original) The embossing system of claim 9, wherein a layer of static vinyl is located between one of the covers to secure the form to one of the covers.

11. (Original) The embossing system of claim 10, wherein an adhesive is located on the cover opposite the cover with the vinyl to secure the stencil.

12. (Currently Amended) The embossing system of claim 9, wherein when the force transfer assembly is in a closed compressed position, ~~there is a~~ the clearance between the form and the stencil is approximately 0.1 millimeter.

13. (Original) The embossing system of claim 9, wherein the force transfer assembly includes at least two apertures so that the force transfer assembly is adapted to be located on pins located on a die press.

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14. (Original) The embossing system of claim 9, wherein the hinge means comprises a plastic material.
15. (Original) The embossing system of claim 9, wherein the hinge means is an adhesive film material.
16. (Original) The embossing system of claim 15, wherein the adhesive film material is a tape material.
17. (Original) The embossing system of claim 12, wherein the hinge is a reduced thickness area joining the first cover and the opposite second cover.
18. (Original) The embossing system of claim 17, wherein the first cover, the second cover, and the hinge are made from a continuous sheet of material.
19. (Original) The embossing system of claim 18, wherein the hinge is made of a clear material.
20. (Original) The embossing system of claim 17, wherein the hinge provides for the clearance between the form and the stencil when the embossing system is operated.
21. (Original) The embossing system of claim 20, wherein the clearance is at least .1 millimeter.
22. (Currently Amended) The method for embossing and embossing material, comprising the steps of:
  - providing a force transfer assembly, which includes a first cover, an opposition second cover, and a hinge for connecting the first cover and the second cover;
  - providing a stencil and an opposing form that is adapted to be positioned internal of the force transfer assembly, the stencil and the form being adapted to sandwich an embossing material between the stencil and the form;

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the force transfer assembly adapted to compress the form against the embossing material and in the direction of the stencil until at least one projection on the form impedes further compression, the at least one projection maintaining a clearance between portions of the form distinct from the at least one projection and the stencil.

23. (Previously Presented) An embossing system, comprising:  
a force transfer assembly comprising:  
a first cover, an opposite second cover; and  
a hinge connecting said first cover and said second cover; and  
said force transfer assembly further comprising a stencil and an opposing form positioned internal of the force transfer assembly, said stencil and said form being adapted to sandwich an embossing material between said stencil and said form;

wherein a layer of static vinyl is located between one of the covers to secure the form or the stencil to one of the covers.

24. (New) The embossing system of claim 1, wherein the form comprises at least one vacuum formed plastic projection.